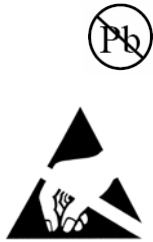


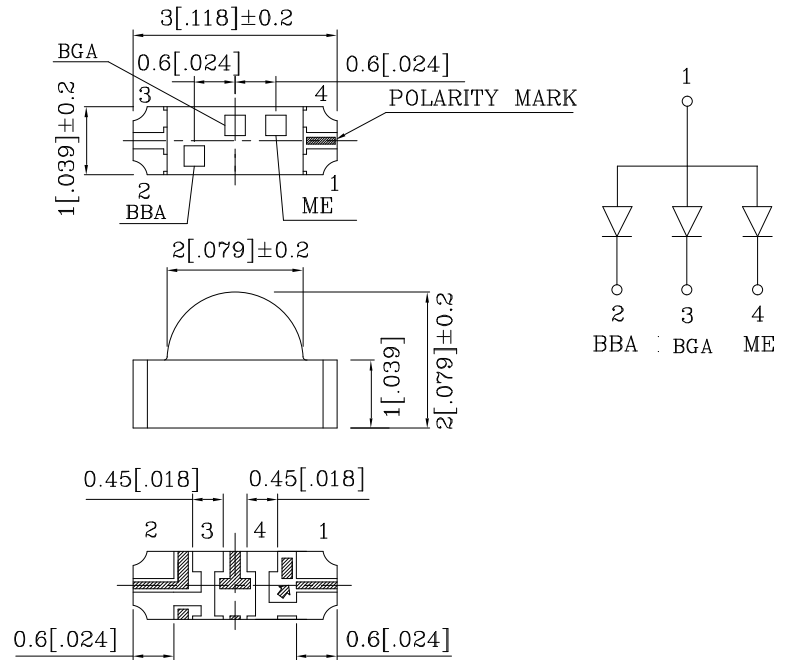
PRELIMINARY SPEC

Features

- LOW POWER CONSUMPTION.
- 3.0mmx1.0mm RIGHT ANGLE SMT LED, 2.0mm THICKNESS.
- CAN PRODUCE ANY COLOR IN VISIBLE SPECTRUM, INCLUDING WHITE LIGHT.
- PACKAGE: 2000PCS/ REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



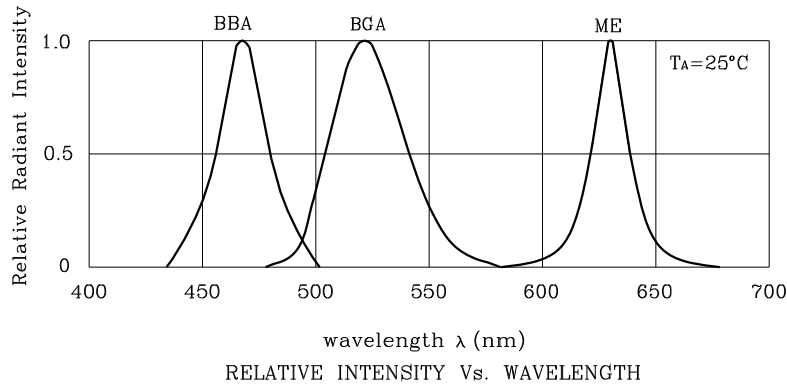
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.1(0.004") unless otherwise noted.
3. Specifications are subject to change without notice.

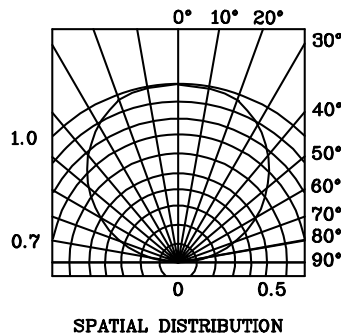
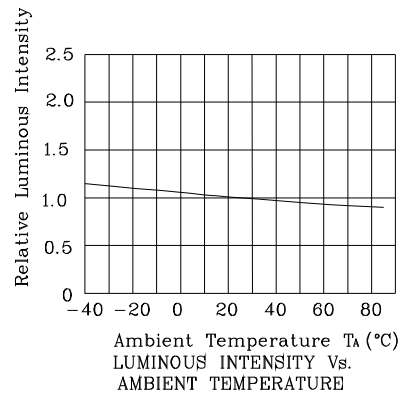
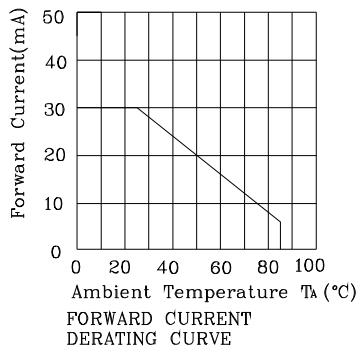
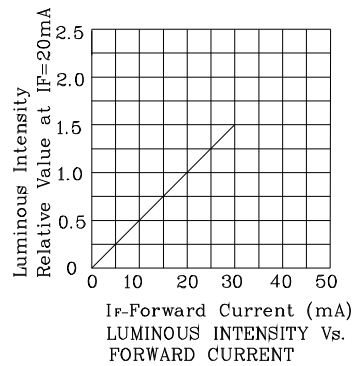
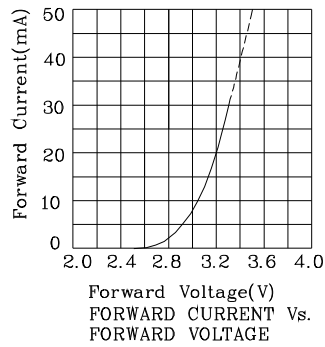
Absolute Maximum Ratings (TA=25°C)		BBA (InGa N)	BGA (InGa N)	ME (InGa AlP)	Unit
Reverse Voltage	VR	5	5	5	V
Forward Current	IF	30	30	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	100	100	195	mA
Power Dissipation	PT	120	120	75	mW
Electrostatic Discharge Threshold (HBM)		1000	1000	-	V
Operating Temperature	TA	-40 ~ +85			°C
Storage Temperature	Tstg	-40 ~ +85			

Operating Characteristics (TA=25°C)		BBA (InGa N)	BGA (InGa N)	ME (InGa AlP)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	3.2	3.2	2.0	V
Forward Voltage (Max.) (IF=20mA)	VF	4.0	4.0	2.5	V
Reverse current (Max.) (VR=5V)	IR	10	10	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λ P	468	520	630	nm
Wavelength of Dominant emission (Typ.) (IF=20mA)	λ D	470	525	621	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	21	35	20	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C	100	100	25	pF

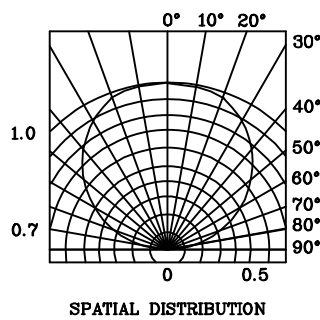
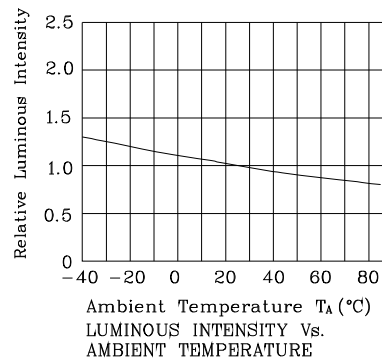
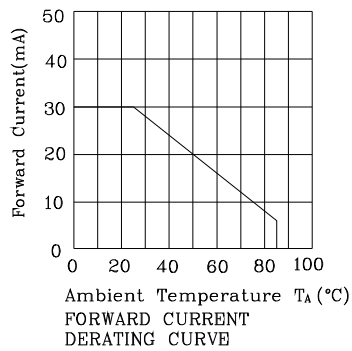
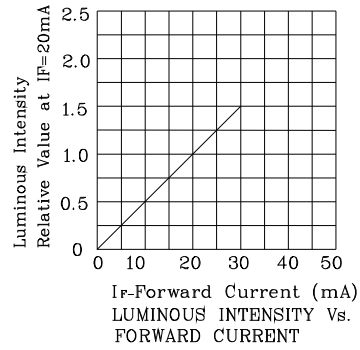
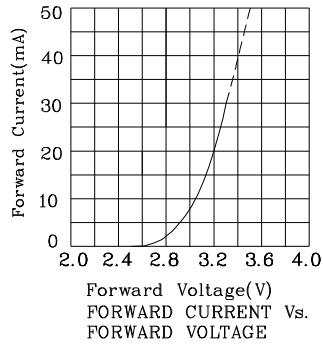
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XZBBABGAME56W-3	Blue	InGaN	Water Clear	18	59	468	120°
	Green	InGaN		70	248	520	
	Red	InGaAlP		110	297	630	



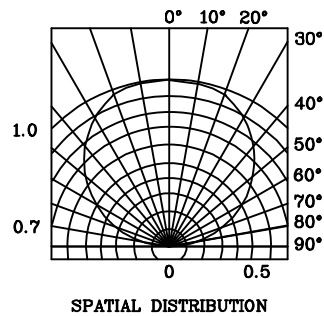
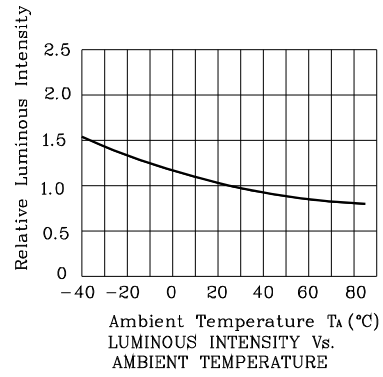
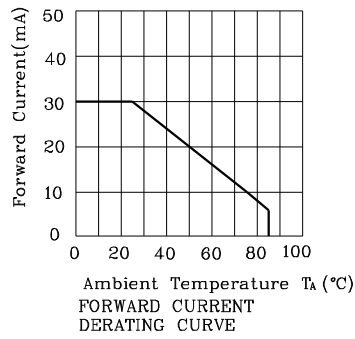
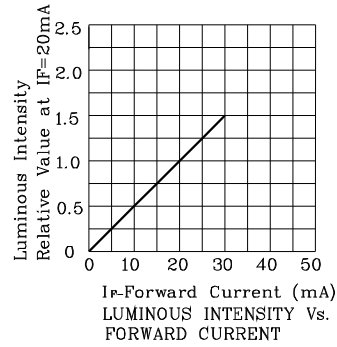
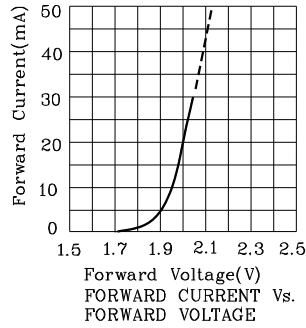
❖ **BBA**



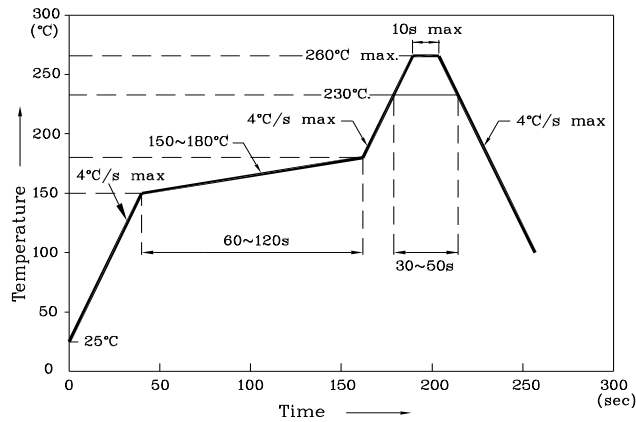
❖ BGA



❖ ME



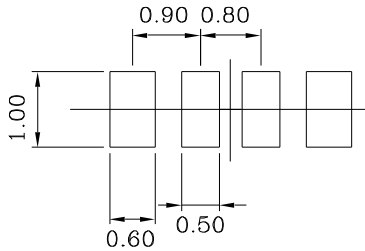
Reflow Soldering Profile For Lead-free SMT Process.



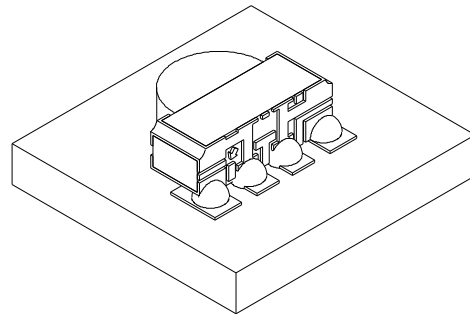
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

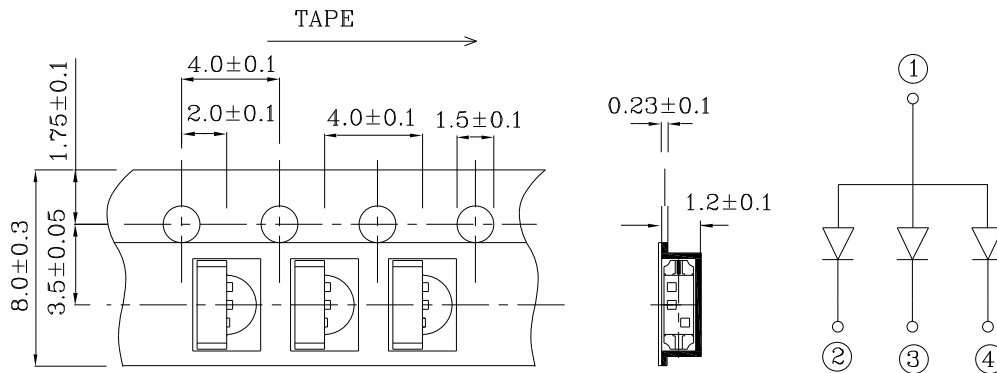
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ± 0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

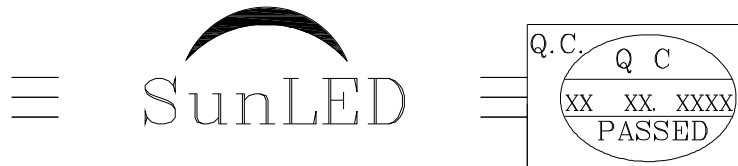
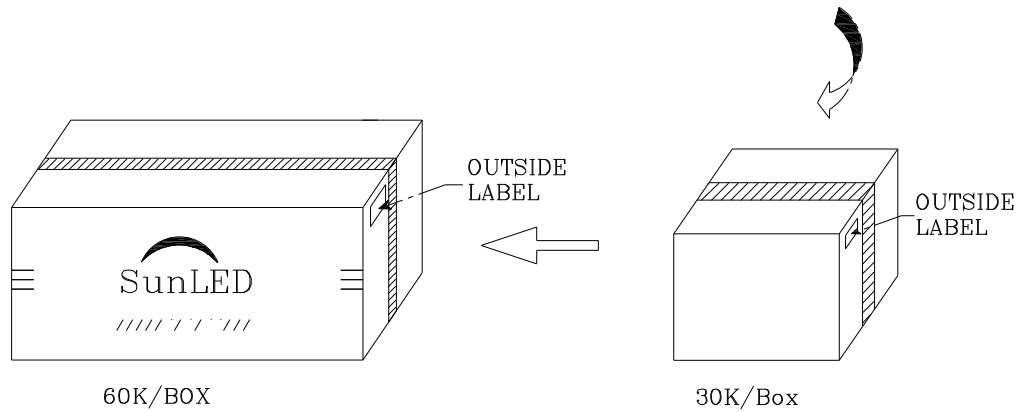
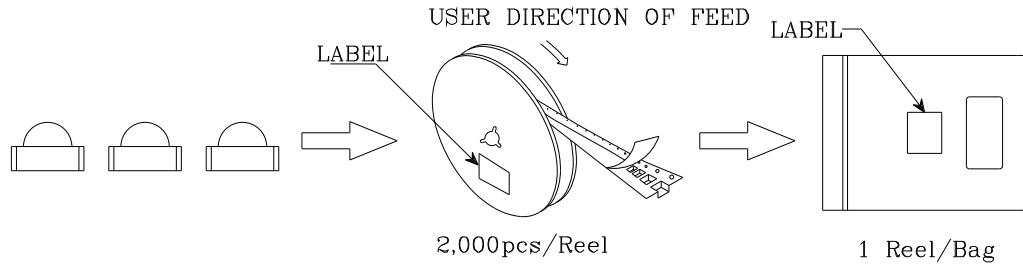
If special sorting is required (e.g. binning based on forward voltage, luminous intensity/ luminous flux or wavelength), the typical accuracy of the sorting process is as follows:


1. Wavelength: +/-1nm
2. Luminous Intensity/ Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

XZBBABGAME56W-3



P/NO : XZxxx56x-3	
QTY : 2,000 pcs	CODE: XXX
S/N : XX	
LOT NO :	
 XXXXXXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	